Product Change Notification

109059 - 02

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #:	**109059 - 02**
Change Title:	**Intel® Server Board S5000PAL, PCN 109059-02, Product Design, Baseboard Heat Sink Update & Fab Spin, Reason for Revision: roadmap change**
Date of Publication:	**December 14, 2008**

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Dec 26, 2008

Description of Change to the Customer:

Reason for Revision: roadmap change

Following changes are being implemented:
(1) Changing the printed circuit board (PCB) to improve the Front Side Bus (FSB) routing for the secondary processor. This design change will result in better signal quality.
(2) Changing the Processor1/Processor2 Voltage Regulator heat sink on the base board from a non-anodized to anodized version. This heat sink is approximately 161mm long, 10.67mm wide and 15.5mm high and comes attached to the server board on top of the Processor1/Processor2 Voltage Regulator (VR) Field Effect Transistors (FETs). The anodized version of the heat sink is black in appearance and has improved thermal conductivity and electrical insulation characteristics. The part number for the VR Heat sink is changing from Intel part number D17794-001 to D57771-003.
(3) Changing base board RevID to 011.

Customer Impact of Change and Recommended Action:

Intel anticipates no impact to customers.

Products Affected / Intel Ordering Codes:

Pre Change Product Code	Pre Change MM#	Pre Change TA	Pre Change PBA	Post Change Product Code	Post Change MM#	Post Change TA	Post Change PBA
S5000PALR	891957	E11675-004	D13607-903	S5000PALR	900354	E11675-005	E50232-100
BB5000PALR	897197	E11677-903	D13607-903	BB5000PALR	900375	E51575-100	E50232-100

Reference Documents / Attachments:

Document:	Location #:

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
November 26, 2008	00	Originally Published PCN
December 3, 2008	01	add BIOS 94 update
December 14, 2008	02	roadmap change